

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5077893

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUN WANG	07/18/2018
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANGJIANG ROAD, PUDONG NEW AREA
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State/Country:	CHINA
Postal Code:	201203
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
Street Address:	18 WENCHANG ROAD
Internal Address:	BEIJING ECONOMIC-TECHNOLOGICAL DEVELOPMENT AREA
City:	BEIJING
State/Country:	CHINA
Postal Code:	100176
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16044949
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SIGNATURE:	/Kieun Sung/
DATE SIGNED:	08/01/2018
Total Attachments: 1 source=SMIC00137US_Assignment_EF#page1.tif	

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I


Jun WANG of 18 Zhangjiang Road
Pudong New Area
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hereby sell, assign and transfer to **Semiconductor Manufacturing International (Shanghai) Corporation**, having a place of business at 18 Zhangjiang Road, Pudong New Area, Shanghai, P.R.C. 201203, and, **Semiconductor Manufacturing International (Beijing) Corporation**, having a place of business at 18 Wenchang Road, Beijing Economic-Technological Development Area, Beijing, China, 100176, its successors and assigns, the entire right, title and interest throughout the world in the invention entitled

REGULATOR CIRCUIT AND MANUFACTURE THEREOF

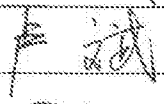
for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisionals, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 18 day of July, 2018.



Jun WANG

WITNESSED:

Signature 
Date 2018.7.18
Type or print name of witness